

E-Beam Wafer Inspection System Market: Global Industry Trends, Share, Size, Growth, Opportunity and Forecast 2023-2028

Market Report | 2023-10-15 | 147 pages | IMARC Group

AVAILABLE LICENSES:

- Electronic (PDF) Single User \$2499.00
- Five User Licence \$3499.00
- Enterprisewide License \$4499.00

Report description:

Market Overview:

The global e-beam wafer inspection system market size reached US\$ 631.3 Million in 2022. Looking forward, IMARC Group expects the market to reach US\$ 1,921.1 Million by 2028, exhibiting a growth rate (CAGR) of 21.44% during 2023-2028.

E-beam wafer inspection system refers to a semiconductor fabrication tool based on electron beam scanning of integrated circuit (IC) components or wafers. It is used for detecting any defects in the wafers before final packaging and is ideal for scanning small sections of a die to identify specific hard-to-detect systematic and random defects. The inspection system scans the wafer and determines coordinates of the defects by comparing it to the image of the adjacent dies. This technique is commonly used while manufacturing compact gadgets, smartphones, laptops and tablets. It is also used for lithographic qualification, wafer dispositioning and reticle quality optimization.

Significant growth in the electronics industry, along with rapid industrialization, is one of the key factors creating a positive outlook for the market. Semiconductor wafers are widely used for manufacturing specialized devices and consumer electronics, thereby increasing the demand for efficient inspection systems. Furthermore, the electrification and automation in automobiles is also driving the market growth. Numerous kinds of wafers are used in automobile components, such as airbag controls, global positioning systems (GPS), anti-lock braking systems (ABS), navigation and display systems and power down and window controls. They are also used for improving automated driving and collision detection technologies, which, in turn, have increased the demand for wafer inspection systems. Moreover, various technological advancements, such as the development of multi-beam e-beam inspection systems that are more efficient and minimize the overall time required for mass production, are projected to drive the market further.

Key Market Segmentation:

Scotts International. EU Vat number: PL 6772247784 tel. 0048 603 394 346 e-mail: support@scotts-international.com www.scotts-international.com

IMARC Group provides an analysis of the key trends in each sub-segment of the global e-beam wafer inspection system market report, along with forecasts at the global, regional and country level from 2023-2028. Our report has categorized the market based on resolution, application and end use.

Breakup by Resolution:

Less than 1 nm 1 nm to 10 nm More than 10 nm

Breakup by Application:

Defect Imaging
Lithographic Qualification
Bare Wafer OQC/IQC
Wafer Dispositioning
Reticle Quality Inspection
Inspector Recipe Optimization

Breakup by End Use:

Communication Devices
Consumer Electronic Equipments
Automotive Parts
Others

Breakup by Region:

North America

United States

Canada

Asia Pacific

China

Japan

India

South Korea

Australia

Indonesia

Others

Europe

Germany

France

United Kingdom

Italy

Spain

Russia

Scotts International. EU Vat number: PL 6772247784

Others

Latin America

Brazil

Mexico

Others

Middle East and Africa

Competitive Landscape:

The report has also analysed the competitive landscape of the market with some of the key players being Aerotech Inc., Applied Materials Inc., ASML Holding N.V., Hitachi Ltd., KLA-Tener Corporation, Lam Research Corporation, Nanotronics Imaging Inc., NXP Semiconductors N.V. (Qualcomm Incorporated), Renesas Electronics Corporation, Synopsys Inc., Taiwan Semiconductor and Teledyne Technologies.

Key Questions Answered in This Report:

How has the global e-beam wafer inspection system market performed so far and how will it perform in the coming years? What has been the impact of COVID-19 on the global e-beam wafer inspection system market?

Page 3/9

What are the key regional markets?

What is the breakup of the market based on the resolution?

What is the breakup of the market based on the application?

What is the breakup of the market based on the end use?

What are the various stages in the value chain of the industry?

What are the key driving factors and challenges in the industry?

What is the structure of the global e-beam wafer inspection system market and who are the key players?

What is the degree of competition in the industry?

Table of Contents:

- 1 Preface
- 2 Scope and Methodology
- 2.10bjectives of the Study
- 2.2Stakeholders
- 2.3Data Sources
- 2.3.1Primary Sources
- 2.3.2Secondary Sources
- 2.4Market Estimation
- 2.4.1Bottom-Up Approach
- 2.4.2Top-Down Approach
- 2.5Forecasting Methodology
- 3 Executive Summary
- 4 Introduction
- 4.10verview
- 4.2Key Industry Trends
- 5 Global E-Beam Wafer Inspection System Market
- 5.1Market Overview
- 5.2Market Performance
- 5.3Impact of COVID-19
- 5.4Market Forecast

Scotts International, EU Vat number: PL 6772247784

tel. 0048 603 394 346 e-mail: support@scotts-international.com

- 6 Market Breakup by Resolution
- 6.1Less than 1 nm
- 6.1.1 Market Trends
- 6.1.2 Market Forecast
- 6.21 nm to 10 nm
- 6.2.1 Market Trends
- 6.2.2 Market Forecast
- 6.3More than 10 nm
- 6.3.1 Market Trends
- 6.3.2 Market Forecast
- 7 Market Breakup by Application
- 7.1Defect Imaging
- 7.1.1 Market Trends
- 7.1.2 Market Forecast
- 7.2Lithographic Qualification
- 7.2.1 Market Trends
- 7.2.2 Market Forecast
- 7.3Bare Wafer OQC/IQC
- 7.3.1 Market Trends
- 7.3.2 Market Forecast
- 7.4Wafer Dispositioning
- 7.4.1 Market Trends
- 7.4.2 Market Forecast
- 7.5Reticle Quality Inspection
- 7.5.1 Market Trends
- 7.5.2 Market Forecast
- 7.6Inspector Recipe Optimization
- 7.6.1 Market Trends
- 7.6.2 Market Forecast
- 8 Market Breakup by End Use
- 8.1Communication Devices
- 8.1.1 Market Trends
- 8.1.2 Market Forecast
- 8.2Consumer Electronic Equipments
- 8.2.1 Market Trends
- 8.2.2 Market Forecast
- 8.3Automotive Parts
- 8.3.1 Market Trends
- 8.3.2 Market Forecast
- 8.40thers
- 8.4.1 Market Trends
- 8.4.2 Market Forecast
- 9 Market Breakup by Region
- 9.1North America
- 9.1.1 United States
 - 9.1.1.1 Market Trends
 - 9.1.1.2 Market Forecast

- 9.1.2 Canada
 - 9.1.2.1 Market Trends
 - 9.1.2.2 Market Forecast
- 9.2Asia Pacific
- 9.2.1 China
 - 9.2.1.1 Market Trends
 - 9.2.1.2 Market Forecast
- 9.2.2 Japan
 - 9.2.2.1 Market Trends
- 9.2.2.2 Market Forecast
- 9.2.3 India
 - 9.2.3.1 Market Trends
 - 9.2.3.2 Market Forecast
- 9.2.4 South Korea
 - 9.2.4.1 Market Trends
- 9.2.4.2 Market Forecast
- 9.2.5 Australia
 - 9.2.5.1 Market Trends
 - 9.2.5.2 Market Forecast
- 9.2.6 Indonesia
 - 9.2.6.1 Market Trends
 - 9.2.6.2 Market Forecast
- 9.2.7 Others
 - 9.2.7.1 Market Trends
 - 9.2.7.2 Market Forecast
- 9.3Europe
- 9.3.1 Germany
 - 9.3.1.1 Market Trends
- 9.3.1.2 Market Forecast
- 9.3.2 France
 - 9.3.2.1 Market Trends
 - 9.3.2.2 Market Forecast
- 9.3.3 United Kingdom
 - 9.3.3.1 Market Trends
 - 9.3.3.2 Market Forecast
- 9.3.4 Italy
 - 9.3.4.1 Market Trends
 - 9.3.4.2 Market Forecast
- 9.3.5 Spain
 - 9.3.5.1 Market Trends
 - 9.3.5.2 Market Forecast
- 9.3.6 Russia
 - 9.3.6.1 Market Trends
 - 9.3.6.2 Market Forecast
- 9.3.7 Others
 - 9.3.7.1 Market Trends
 - 9.3.7.2 Market Forecast

- 9.4Latin America
- 9.4.1 Brazil
 - 9.4.1.1 Market Trends
 - 9.4.1.2 Market Forecast
- 9.4.2 Mexico
 - 9.4.2.1 Market Trends
 - 9.4.2.2 Market Forecast
- 9.4.3 Others
 - 9.4.3.1 Market Trends
 - 9.4.3.2 Market Forecast
- 9.5Middle East and Africa
- 9.5.1 Market Trends
- 9.5.2 Market Breakup by Country
- 9.5.3 Market Forecast
- 10 SWOT Analysis
- 10.10verview
- 10.2Strengths
- 10.3Weaknesses
- 10.40pportunities
- 10.5Threats
- 11 Value Chain Analysis
- 12 Porters Five Forces Analysis
- 12.10verview
- 12.2Bargaining Power of Buyers
- 12.3Bargaining Power of Suppliers
- 12.4Degree of Competition
- 12.5Threat of New Entrants
- 12.6Threat of Substitutes
- 13 Price Analysis
- 14 Competitive Landscape
- 14.1Market Structure
- 14.2Key Players
- 14.3Profiles of Key Players
- 14.3.1Aerotech Inc.
 - 14.3.1.1 Company Overview
- 14.3.1.2 Product Portfolio
- 14.3.2Applied Materials Inc.
 - 14.3.2.1 Company Overview
 - 14.3.2.2 Product Portfolio
 - 14.3.2.3 Financials
 - 14.3.2.4 SWOT Analysis
- 14.3.3ASML Holding N.V.
 - 14.3.3.1 Company Overview
 - 14.3.3.2 Product Portfolio
 - 14.3.3.3 Financials
 - 14.3.3.4 SWOT Analysis
- 14.3.4Hitachi Ltd.

14.3.4.1 Company Overview

14.3.4.2 Product Portfolio

14.3.4.3 Financials

14.3.4.4 SWOT Analysis

14.3.5KLA-Tener Corporation

14.3.5.1 Company Overview

14.3.5.2 Product Portfolio

14.3.5.3 Financials

14.3.5.4 SWOT Analysis

14.3.6Lam Research Corporation

14.3.6.1 Company Overview

14.3.6.2 Product Portfolio

14.3.6.3 Financials

14.3.6.4 SWOT Analysis

14.3.7Nanotronics Imaging Inc.

14.3.7.1 Company Overview

14.3.7.2 Product Portfolio

14.3.8NXP Semiconductors N.V. (Qualcomm Incorporated)

14.3.8.1 Company Overview

14.3.8.2 Product Portfolio

14.3.8.3 Financials

14.3.8.4 SWOT Analysis

14.3.9Renesas Electronics Corporation

14.3.9.1 Company Overview

14.3.9.2 Product Portfolio

14.3.9.3 Financials

14.3.9.4 SWOT Analysis

14.3.10Synopsys Inc.

14.3.10.1 Company Overview

14.3.10.2 Product Portfolio

14.3.10.3 Financials

14.3.10.4 SWOT Analysis

14.3.11Taiwan Semiconductor

14.3.11.1 Company Overview

14.3.11.2 Product Portfolio

14.3.11.3 Financials

14.3.11.4 SWOT Analysis

14.3.12Teledyne Technologies

14.3.12.1 Company Overview

14.3.12.2 Product Portfolio

14.3.12.3 Financials

14.3.12.4 SWOT Analysis



E-Beam Wafer Inspection System Market: Global Industry Trends, Share, Size, Growth, Opportunity and Forecast 2023-2028

Market Report | 2023-10-15 | 147 pages | IMARC Group

To place an Order w	vith Scotts International:			
Print this form				
☐ - Complete the	relevant blank fields and sign			
Send as a scar	nned email to support@scotts-interna	ational.com		
ORDER FORM:				
Select license	License			Price
	Electronic (PDF) Single User			\$2499.00
	Five User Licence			\$3499.00
	Enterprisewide License			\$4499.00
			VAT	
			Total	
*Places circle the release	vant license ention. For any questions ple	usea cantact cunnart@c	cotts international com or 0049 603 3	04.346
□** VAT will be added	vant license option. For any questions ple at 23% for Polish based companies, indiv	viduals and EU based co		
** VAT will be added Email*		riduals and EU based co		
□** VAT will be added		viduals and EU based co		
** VAT will be added Email*		riduals and EU based co		
** VAT will be added Email* First Name*		riduals and EU based co	ompanies who are unable to provide a	
** VAT will be added Email* First Name* Job title*		Phone* Last Name*	ompanies who are unable to provide a	
Email* First Name* Job title* Company Name*		Phone* Last Name* EU Vat / Tax ID / N	ompanies who are unable to provide a	

Scotts International. EU Vat number: PL 6772247784

tel. 0048 603 394 346 e-mail: support@scotts-international.com www.scotts-international.com

Signature

L	